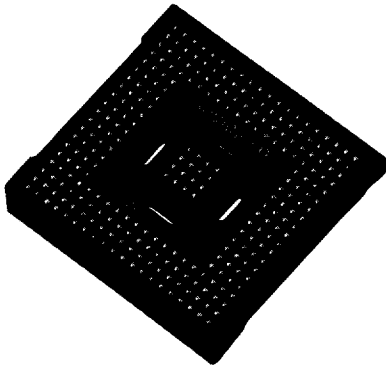


BGA Sockets



Features:

- Advanced® exclusive eutectic solder ball terminals offer superior SMT processing.
- Uses same footprint as BGA device.
- Proven long-term performance in vigorous temperature cycling applications - solder ball terminal absorbs TCE mismatch.
- Closed bottom socket terminal for 100% anti-wicking of solder.
- Gold contacts allow gold/gold interconnections to male Adapter pins.
- Low insertion force socket with multi-fingered high reliability Beryllium Copper contacts.
- Coplanarity consistently under .006 inch industry standard.
- In-house Tape and Reel packaging available.
- See page 4 for How It Works.

Terminals and Contacts:

Terminals: Brass - Copper Alloy (C36000)
ASTM-B-16

Contacts: Beryllium Copper - Copper Alloy (C17200), ASTM-B-194

Plating:

G - Gold over Nickel

Body Material:

M - Molded High Temp. Glass Filled Thermoplastic (P.P.S.), U.L. Rated 94V-O, -60°C to 260°C (-76°F to 500°F)

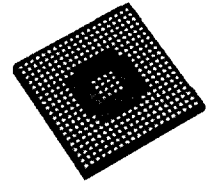
F - FR-4 Glass Epoxy, U.L. Rated 94V-O

Solder:

63Sn/37Pb, Eutectic, 183°C (361.4°F)

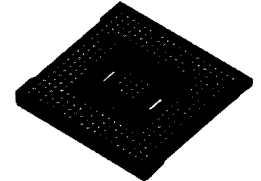
Standard Socket (S):

- Mates with Standard Adapter (A)
- Socket size same size as BGA device body
- Use with SMT Adapter for LGA and reworked BGA device socketing



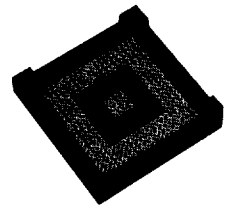
Extraction Socket (SB):

- Mates with Extraction Slot Adapter (AX)
- Socket size equals BGA body + .079/(2.0)
- Protects valuable PCB during device/adapter extraction - tool never touches PCB
- Available in 1.0, 1.27 and 1.5mm pitch only

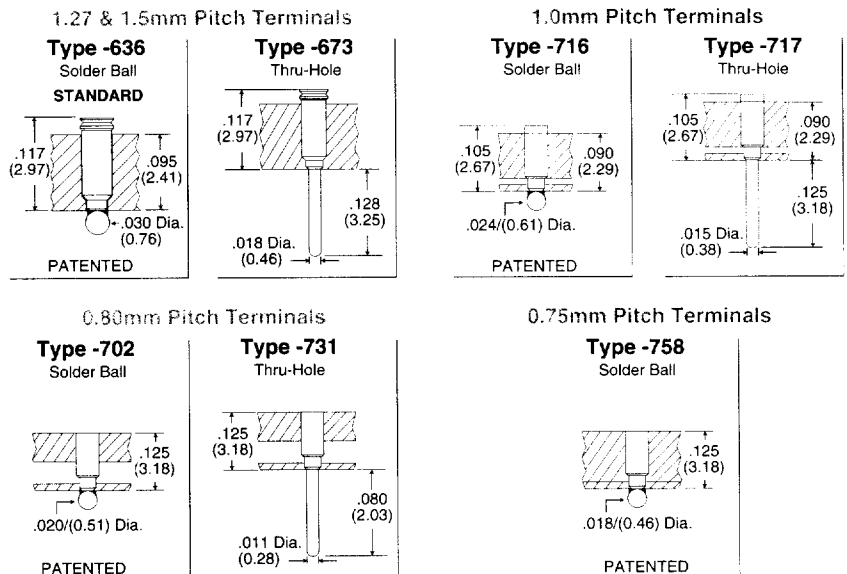


Guide Post Socket (SG):

- Integral molded corners allow accurate positioning of device/adapter assembly in blind-mating applications.
- Mates with Extraction Slot Adapter (AX)
- Socket size equals BGA body + .276/(7.00)
- Available in 1.27 and 1.5mm pitch only



Terminals:



How To Order

